

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	257	257/789.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1991	257/787.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	942	257/783.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	904	257/707.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	123	L1 and resin and filler	US-PGPUB; USPAT
6	BRS	L6	225	257/E23.121.ccls.	US-PGPUB; USPAT; USOCR
7	BRS	L7	164	L6 and resin and filler	US-PGPUB; USPAT
8	BRS	L8	0	((die or chip or element) and (resin or underfill or bonding or encapsula\$2) and (filler or particle or spacer) and thick and plate and (ball or bump)).clm.	US-PGPUB

9	BRS	L9	4	((die or chip or element) and (resin or underfill or bonding or encapsula\$2) and (filler or particle or spacer) and thick and substrate and (ball or bump)).clm.	US-PGPUB
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	Type	L #	Hits	Search Text	DBs
10	BRS	L10	181	257/789.ccls.	EPO; JPO; DERWENT ; IBM_TDB